

AMENDMENTS TO THE CLAIMS

1. (Previously presented) A semiconductor package comprising:
a substrate including a redundant bond finger, an added bond finger connected to a redundant solder ball pad;
a semiconductor chip having an added bond pad attached to the substrate;
a normal wire bonding unit coupled between the added bond pad and the redundant bond finger; and
an added wire bonding unit coupled between the redundant bond finger and the added bond finger,
wherein the added bond pad is electrically connected to the redundant solder ball pad via the redundant bond finger and the added bond finger.

2. (Original) The semiconductor package of claim 1, further comprising:
an encapsulant for encapsulating the semiconductor chip, the normal and added wire bonding units.

3. (Original) The semiconductor package of claim 2, further comprising:
a solder ball connected to the redundant solder ball pad.

4. (Original) The semiconductor package of claim 1, wherein the substrate is a single-layer substrate on which a printed circuit pattern is formed.

5. (Original) The semiconductor package of claim 1, wherein the substrate is a double-layer substrate or a multi-layer substrate.

6. (Original) The semiconductor package of claim 1, wherein a solder mask is not formed on the added bond finger.

7. (Original) The semiconductor package of claim 1, wherein the added wire bonding unit is formed over the substrate.

8. (Original) The semiconductor package of claim 1, wherein the added wire bonding unit is formed on an outer region of the substrate on which the semiconductor chip is mounted.

9. (Original) The semiconductor package of claim 1, wherein the added wire bonding unit is one unit or a plurality of units.

10. (Original) The semiconductor package of claim 1, wherein the semiconductor chip is attached to the substrate using an adhesive.

11. (Cancelled)

12. (Original) The semiconductor package of claim 1, wherein the added bond finger has the same pad shape as that of the redundant bond finger.

13. (Previously presented) A semiconductor package comprising:
a substrate including a first printed circuit pattern connected to a redundant bond finger and a second printed circuit pattern connected to a redundant solder ball pad;
a semiconductor chip attached to the substrate; and
an added wire bonding unit coupled between the first printed circuit pattern to the second printed circuit pattern to electrically connect the redundant bond finger to the redundant solder ball pad.

14. (Original) The semiconductor package of claim 13, further comprising:
an encapsulant for encapsulating the semiconductor chip and the added wire bonding unit.

15. (Original) The semiconductor package of claim 14, further comprising:
a solder ball connected to the redundant solder ball pad.

16. (Original) The semiconductor package of claim 13, wherein the first and second printed circuit patterns each have a width that enables wire bonding to be performed thereon.

17-25. (Cancelled)

26. (Previously presented) A semiconductor package comprising:
a semiconductor chip having an added bond pad;

a substrate having a redundant bond finger and an added bond finger connected to a redundant solder ball pad;

a normal wire bonding unit coupled between the added bond pad and the redundant bond finger; and

an added wire bonding unit coupled between the redundant bond finger and the added bond finger such that the added bond pad is electrically connected to the redundant solder ball pad via the redundant bond finger and the added bond finger.

27. (Previously presented) The semiconductor package of claim 26, wherein the added bond finger is not directly connected to the added bond pad.